

Cleaning Instructions



It is recommended to clean the process bowl when processing is completed at the end of the day. Daily cleanup is a good practice and it prevents the excessive buildup of material over time. An appropriate solvent or cleaner should be used (wear all required personal protective equipment). It is recommended to leave the N2 or CDA supply on so that the seal purge is constantly present and to leave the lid in the up position to allow drying of residual moisture. Any questions regarding the maintenance of your spin processor can be addressed at support@laurell.com

- **Care should be taken not to flood the process chamber during cleaning.**
- If unit is equipped with a vacuum chuck, **it is important not to allow chemicals or chemical cleaners to enter the vacuum path.**
- **NEVER flood or spray solvent such as acetone or any other type of cleaner directly onto the keypad surface. Doing so may cause keypad failure.** Always wet a wipe or cloth with the solvent and gently wipe the keypad surface.

NOTE!

The vacuum path is not designed for any pressure. Air pressure or any liquid forced or drawn into the vacuum chuck will very likely damage the vacuum sensor, seals, motor and electronics. This type of damage is not covered by our warranty



- **CLEANING** - Clean, rinse, then dry your spin processor after each use, taking care to prevent any chemicals from entering the vacuum path. A good practice is to cover the chuck during bowl cleaning. This can be done with a wafer with vacuum turned on or use a cover such as Petri dish.
- **ALSO DO NOT FLOOD THE AREA BETWEEN THE STATIONARY SEAL AND THE ROTATING SEAL. THIS CAN CAUSE MOTOR OR ELECTRONICS DAMAGE.** See Fig. 4-1 below.
- Do not fill up or overflow the process chamber or bowl – fluids must not be permitted to flow under the substrate.
- If the chuck face shows signs of chemical residue, remove and clean immediately. Cleaning the o-ring surface will improve the seal. **Examine and adjust your process to prevent such occurrences.**

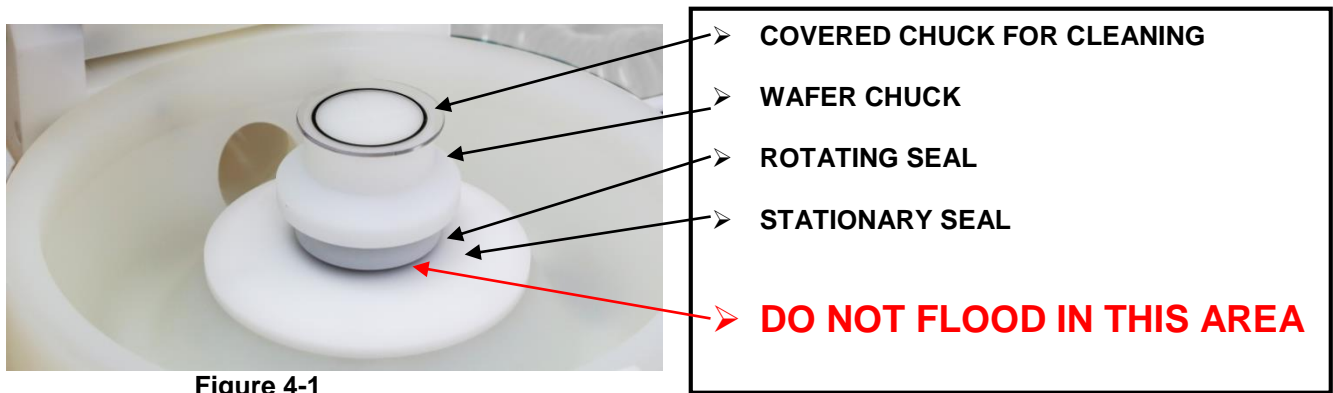


Figure 4-1

- Do not at any time force fluids or pressuring gas in the center of the vacuum chuck. Cleaning the vacuum path in this manner is dangerous and can cause significant damage to your spin processor.